

## **METHOD AND DEVICE FOR MANUFACTURING BONDING PADS FOR CHIP SCALE PACKAGING**

### **ABSTRACT OF THE DISCLOSURE**

An integrated circuit chip and method of manufacture. The chip has a  
5 substrate, e.g., silicon, silicon on insulator, epitaxial wafer. The substrate has a plurality of  
chip structures. A plurality of bonding pads are disposed on the substrate. Each of the  
bonding pads is formed from an aluminum bearing material or other like material. A surface  
region is formed on each of the bonding pads. An under bump metal layer ("UBM") is  
overlying the surface region. A wetting layer is formed overlying the under bump metal  
10 layer. The wetting layer comprises a plurality of protrusions extending out of the wetting  
layer and disposed spatially on the wetting layer. A bump layer is formed overlying the  
wetting layer and is mechanically coupling to the plurality of protrusions.

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